



### 产品名称 Product name

- ▶ 3.2\*4.2包脚
- ▶ 3.2 \* 4.2 Wrap leg

### 产品应用场景 Product application scenario

- ▶ 电子通讯/数码产品/家用电器
- ▶ 外围设备/汽车/医疗设备等.
- ▶ Electronic communication/digital products/household appliance peripherals/AuTomobile/medical equipment, etc

## 产品参数/Product parameters

额定电流 (Rated current): 50mA @ 12 VDC

寿命实验 (Life Test) : 100,000 cycles typical

接触电阻 (Contact Resistance) : 100MΩ max.

绝缘电阻 (Insulation Resistance) : 100MΩ min.

按键行程 (Key stroke) : 0.20±0.1mm

驱动力 (Actuation Force) : 100gf, 160gf, 260gf

工作温度 (Operating Temperature) : -20° C to 70° C

介电强度 (Dielectric Strength) : AC 250V 50HZ 1 minute

存储温度 (Storage Temperature) : -30° C T0+80° C

最小包装 (DMinimum package) : 3000PCS (卷装)

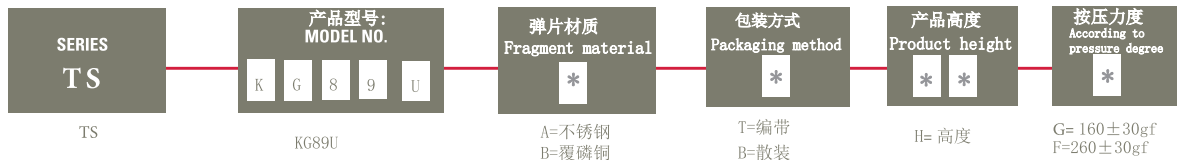
### 材质/MATERIALS:

No.	名称 NAME	材料 MATERIAL	表面处理/颜色 Surface treatment/color
①	按钮 Button	PPA	白色 white
②	盖板 Cover plate	F. Ag/SUS	镀银 Plate with silver
③	底座 Base	LCP	白色 white
④	弹片 Shrapnel	F. Ag/SUS	镀银 Plate with silver
⑤	端子 Terminal	F. Ag/C5210	镀银 Plate with silver

### 产品高度/Product height:

产品高度 (Product height)	
Code	H
25	2.5

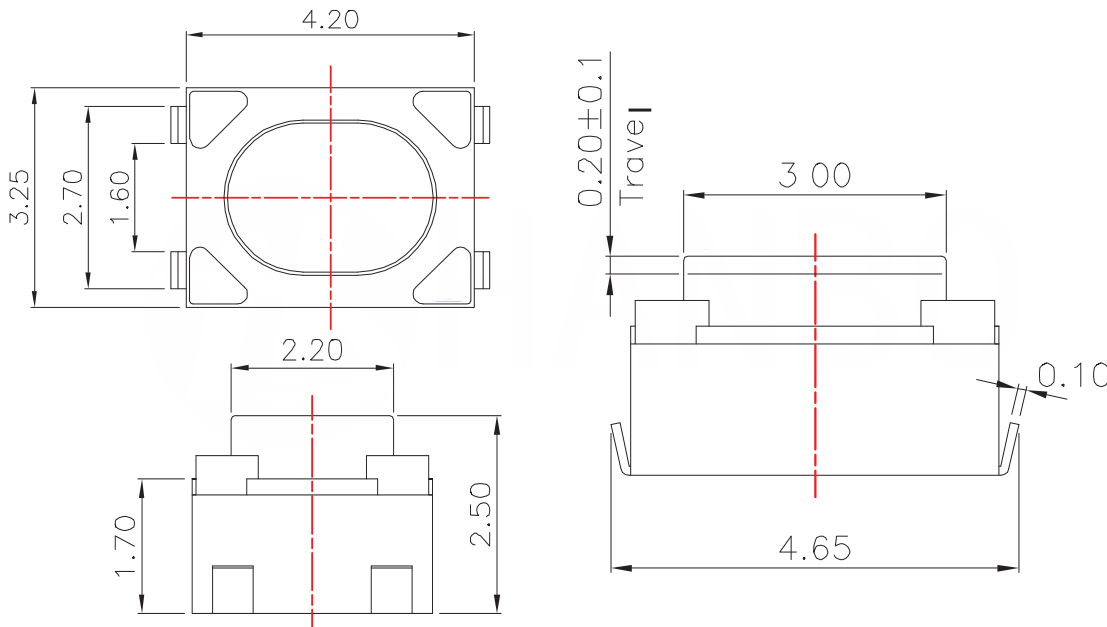
### 产品编号/Product No

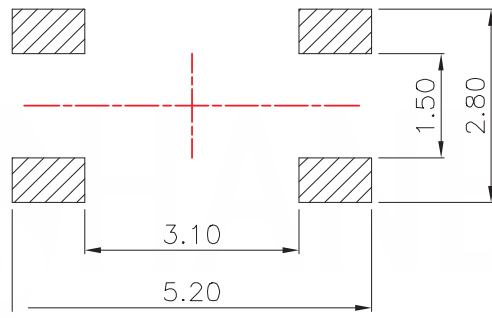
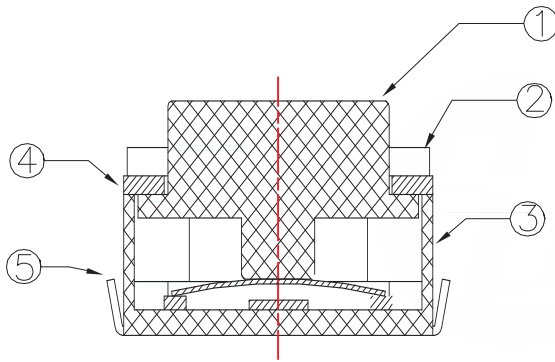


### 产品订购号示意图/Schematic diagram of product order number

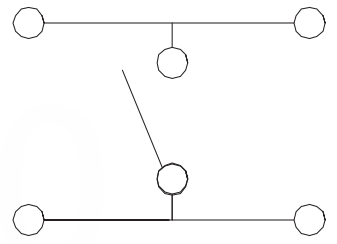
Schematic diagram of product order number: TS-KG89U-AT25F

### 产品外形尺寸图/Outline dimension drawing of product





PCB Layout(Pattern Side)

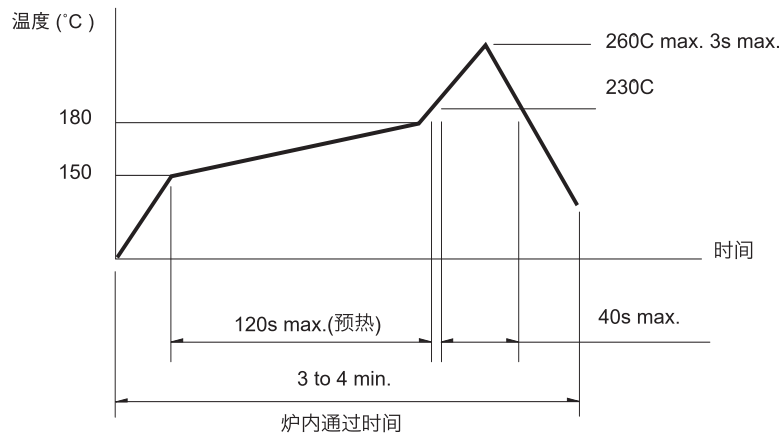


Circuit diagram

焊接条件/Welding conditions

回流焊时/During reflow soldering

适用于表面贴装型温度分布/Applicable to surface mount temperature distribution



注/notes

- 关于详细条件，请于本公司的产品规格书进行确认。  
Please confirm the detailed conditions in our product specification
- 根据贴面焊槽的种类，条件不同结果不同，请事先充分进行确认之后使用。  
According to the type of veneer welding groove and different conditions, the results are different. Please fully confirm before using.

自动浸焊式/Automatic dip welding

项目	条件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷电路板焊接面的周围温度 100°C max.
预热温度时间	60s max.
焊接温度	260°C max.
焊接浸渍时间	5s max.
焊接次数	2 times max.

注/notes

- 请不要从轻触开关上面浸入助焊剂。  
Do not immerse the flux on the touch switch
- 请不要事前在开关端子及印刷电路板的零部件贴装面上涂助焊剂。  
Please do not apply flux on the mounting surface of switch terminals and printed circuit board components in advance
- 进行第 2 次焊接时，应在开关回复到常温之后进行。  
The second welding shall be carried out after the switch returns to normal temperature.

手焊式/Hand welded

项目	条件
焊接温度	350°C max.
焊接浸渍时间	3s max.
焊剂斗容量	60W max.